

Trench IGBT Modules

SKM150MLI066TAT

Target Data

Features

- Homogeneous Si
- Trench = Trenchgate technology
- V_{CE(sat)} with positive temperature coefficient
- Integrated NTC temperature sensor

Typical Applications*

- UPS
- 3 Level Inverter

Remarks

- Case temperature limited to T_c =125°C max
- Recommended T_{op} = -40..+150°C
- T_{vj} is intended as absolute maximum rating
- Fig.2 is referred to IGBT current capability



Absolut	e Maximum Ratings	T _{case}	= 25°C, unless otherwise	specified
Symbol	Conditions		Values	Units
IGBT				
V_{CES}	T _j = 25 °C T _i = 175 °C		600	V
I _C	T _j = 175 °C	T _c = 25 °C	200	Α
		T _c = 80 °C	150	Α
I _{CRM}	I _{CRM} =2xI _{Cnom}		300	Α
V_{GES}			± 20	V
t _{psc}	V_{CC} = 360 V; $V_{GE} \le$ 15 V; V_{CES} < 600 V	T _j = 150 °C	6	μs
Inverse	Diode			
I _F	T _j = 150 °C	$T_c = 25 ^{\circ}C$	200	Α
		T _c = 80 °C	145	Α
I _{FRM}	I _{FRM} =2xI _{Fnom}		300	Α
I _{FSM}	t _p = 10 ms; half sine wave	T _j = 150 °C	1080	Α
Freewho	eeling Diode			
I_{F}	T _j = 150 °C	T_c = 25 °C	200	Α
		T _c = 80 °C	145	Α
I _{FRM}	I _{FRM} =2xI _{Fnom}		300	Α
I _{FSM}	t _p = 10 ms; half sine wave	T _j = 150 °C	1080	Α
Module	<u> </u>			
I _{t(RMS)}			500	Α
T _{vj}			- 40 + 175	°C
T _{stg}			- 40 + 125	°C
V _{isol}	AC, 1 min.		2500	V

Characteristics T _{case} =			25°C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 2.4$ mA		5	5,8	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C			0,0076	mA
I _{GES}	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}$	T _j = 25 °C			600	nA
V _{CE0}		T _j = 25 °C		0,9	1	V
		T _j = 150 °C		0,85	0,9	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		3,6	6	mΩ
		T _j = 150°C		5,4	7,6	$m\Omega$
V _{CE(sat)}	I _{Cnom} = 150 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		1,45	1,9	V
		$T_j = 150^{\circ}C_{chiplev.}$		1,7	2,1	V
C _{ies}				9,2		nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,57		nF
C _{res}				0,27		nF
R _{Gint}	$T_j = ^{\circ}C$			2		Ω
t _{d(on)}				140		ns
t _r	R_{Gon} = 4,4 Ω	$V_{CC} = 300V$		89		ns
E _{on}	di/dt = 3400 A/μs	I _C = 150A		1,7		mJ
t _{d(off)}	$R_{Goff} = 4.4 \Omega$	T _j = 150 °C		433		ns
t _f	di/dt = 3400 A/μs	V _{GE} = -15V/+15V		116		ns
E _{off}				5,1		mJ
R _{th(j-c)}	per IGBT			0,29		K/W



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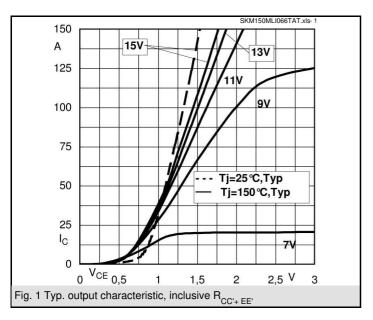
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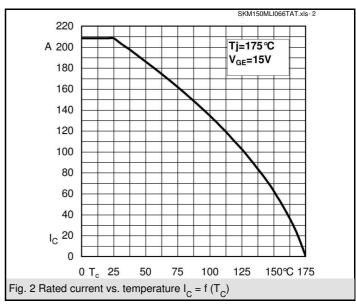
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Characteristics									
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Symbol	Conditions		min.	typ.	max.	Units			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Inverse Diode									
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$V_F = V_{EC}$	I_{Fnom} = 150 A; V_{GE} = 0 V			1,35	1,6	V			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			$T_j = 150 ^{\circ}C_{chiplev.}$		1,35	1,6	V			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V_{F0}				1	1,1	V			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$							V			
$\begin{array}{c} Q_{rr} \\ E_{rr} \\ \\ V_{GE} = -8 \ V; \ V_{CC} = 300 \ V \\ \hline \\ R_{th(j-c)D} \\ \\ \hline \\ Pree-wheeling \ diode \ (Neutral \ Clamp \ Diode) \\ V_F = V_{EC} \\ \hline \\ V_{F} = V_{EC} \\ \hline \\ V_{F0} \\ \hline \\ V_{F0$	r_F				,	3,3	mΩ			
$\begin{array}{c} Q_{rr} \\ E_{rr} \\ \\ V_{GE} = -8 \ V; \ V_{CC} = 300 \ V \\ \hline \\ R_{th(j-c)D} \\ \\ \hline \\ Pree-wheeling \ diode \ (Neutral \ Clamp \ Diode) \\ V_F = V_{EC} \\ \hline \\ V_{F} = V_{EC} \\ \hline \\ V_{F0} \\ \hline \\ V_{F0$			T _j = 150 °C		3	4	mΩ			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		I _F = 150 A	T _j = 150 °C							
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	E _{rr}	$V_{GE} = -8 \text{ V}; V_{CC} = 300 \text{ V}$					mJ			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	R _{th(j-c)D}	per diode			0,52		K/W			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		eling diode (Neutral (Clamp Diode)				•			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$V_F = V_{EC}$	I_{Fnom} = 150 A; V_{GE} = 0 V			1,35	1,6	V			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			$T_j = 150 ^{\circ}C_{\text{chiplev.}}$		1,35	1,6	V			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V_{F0}		T _j = 25 °C		1	1,1	V			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$					0,9	1	V			
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	r_{F}				2,3	3,3	V			
$\begin{array}{cccccccccccccccccccccccccccccccccccc$			T _j = 150 °C		3	4	V			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			T _j = 150 °C				1			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		·					The state of the s			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$					2		<u> </u>			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$R_{th(j-c)FD}$	per diode			0,52		K/W			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$R_{th(c-s)}$	per module				0,038	K/W			
w 310 g Temperature sensor R_{100} T_s =100°C (R_{25} =5kΩ) 493±5% Ω	M _s	to heat sink M6		3		5	Nm			
Temperature sensor R_{100} T_s =100°C (R_{25} =5kΩ) 493±5% Ω	M _t	to terminals M6		2,5		5	Nm			
R_{100} $T_s = 100$ °C $(R_{25} = 5k\Omega)$ 493±5% Ω	w					310	g			
R_{100} $T_s = 100$ °C $(R_{25} = 5k\Omega)$ 493±5% Ω	Tempera	ture sensor	-				•			
	R ₁₀₀				493±5%		Ω			
							K			

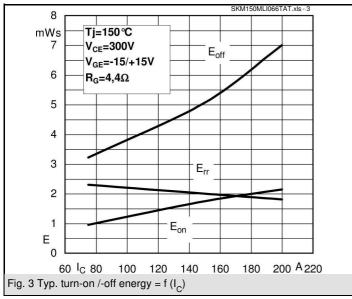
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

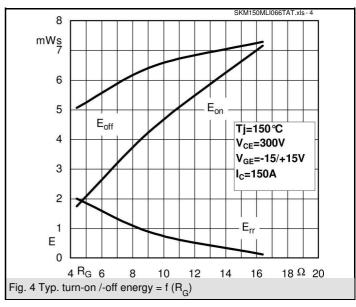
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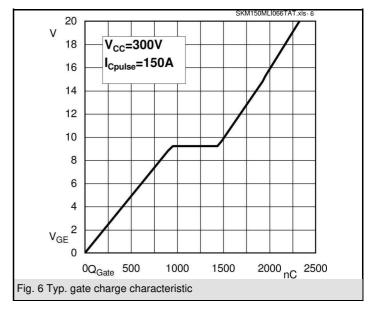


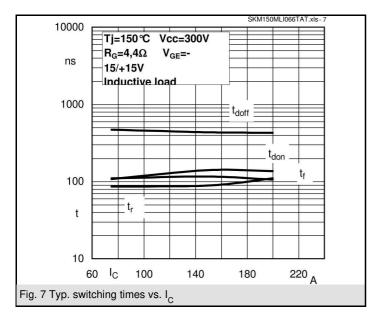


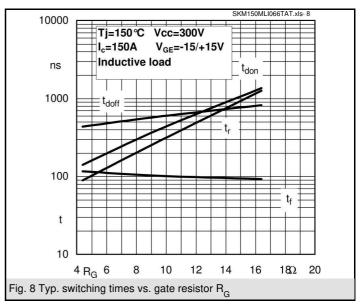


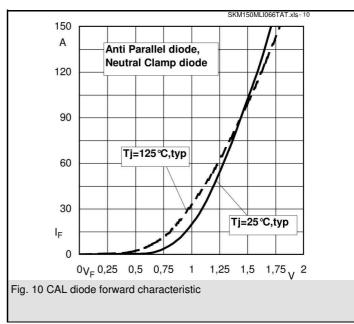




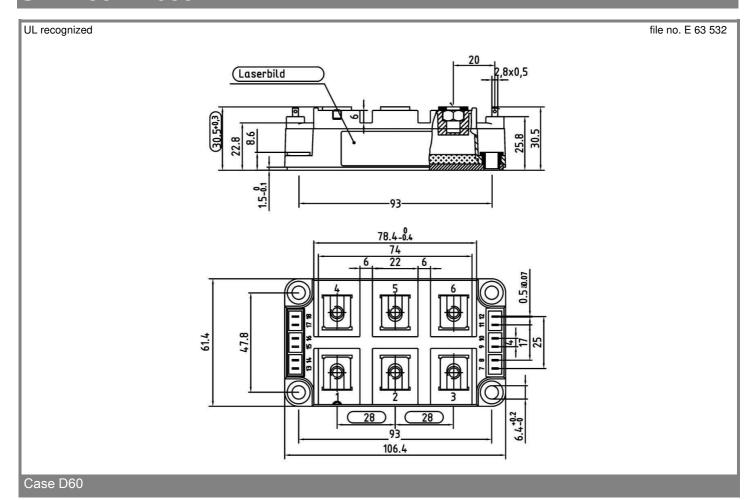


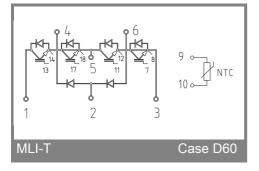






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